

**IN THE CLAIMS:**

1           1.    (Currently Amended) A wire loop comprising:  
2                   a wire connecting a first bonding point and a second bonding point therethrough;  
3                   said wire including a ball bonded to said first bonding point, a neck portion  
4 adjacent to said ball and a major portion extending from said neck portion to said second  
5 bonding point;  
6                   wherein said major portion of said wire has a crushed part formed in proximity to  
7 said neck portion by crushing the part of said wire together with a top portion of said ball so that  
8 the wire extends in one direction away from said bonding point at a first position and the crushed  
9 part extends in another direction to contact the bonding point at a second position.

1           2.    (Original) The wire loop as defined in claim 1, wherein said neck portion  
2 includes a first kink formed by a part of said neck portion being doubled over.

1           3.    (Original) The wire loop as defined in claim 1, wherein said major portion of said  
2 wire includes a horizontal portion extending in a substantially horizontal direction from said  
3 neck portion and an inclined portion which extends from said horizontal portion to said second  
4 bonding point and which has an end thereof bonded to said second bonding point; and  
5                   said inclined portion is connected to said horizontal portion through a second kink  
6 formed in a part of said wire therebetween.

1           4.    (Original) The wire loop as defined in claim 2, wherein said major portion of said  
2 wire includes a horizontal portion extending in a substantially horizontal direction from said  
3 neck portion and an inclined portion which extends from said horizontal portion to said second  
4 bonding point and which has an end thereof bonded to said second bonding point; and

5           said inclined portion is connected to said horizontal portion through a second kink  
6   formed in a part of said wire therebetween.

1           5.     (Original) The wire loop as defined in claim 2, wherein said neck portion  
2   includes at least one additional doubled over kink like said first kink.

1           6-13.   (Cancelled)

1           14.    (Currently Amended) A semiconductor device comprising:  
2                a first bonding point;  
3                a second bonding point spaced from the first bonding point; and  
4                a wire bonded to said first bonding point and said second bonding point to  
5   connect said first bonding point and said distal second bonding point therethrough;  
6                wherein said wire includes a ball bonded to said first bonding point, a neck  
7   portion adjacent to said ball and a major portion extending from said neck portion to said distal  
8   second bonding point; and  
9                wherein said major portion of said wire has a crushed part formed in proximity to  
10 and at a distal side of said neck portion by crushing ~~the~~ a part of said wire together with a top  
11 portion of said ball.

1           15.    (Original) The semiconductor device as defined in claim 14, wherein said neck  
2   portion includes a first kink formed by a part of said neck portion being doubled over.

1           16.    (Original) The semiconductor device as defined in claim 15, wherein said neck  
2   portion includes at least one additional doubled over kink like said first kink.

1        17.    (Previously Presented) An improved wire loop connector for electrical  
2 connection between a semiconductor device and a lead frame comprising:

3                a wire body of a predetermined length;

4                a first end of the wire body for electrical connection with the semiconductor  
5 device having an immediately adjacent first overlaid length of the wire body to double the  
6 overall thickness of the wire body at the electrical connection; and

7                a second distal end of the wire body for electrical connection with the lead frame  
8 having a thickness of the wire body wherein the height of the wire body relative to a distance  
9 above the semiconductor device is restricted.

1        18.    (Previously Presented) The improved wire loop connection of Claim 17 further  
2 including at the first end of the wire body a second overlaid length of the wire body wherein a  
3 thickness is quadruple the overall thickness of the wire body.

1        19.    (Previously Presented) The improved wire loop connection of Claim 18 wherein  
2 the wire body has been bent three times to integrally form the quadruple overall thickness with  
3 each bent length closed upon another length of the wire body.